

SOP022-2

land grid array package; 350 lands

10 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LGA350
Package type industry code	LGA350
Package style descriptive code	LGA (land grid array package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-8-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		32.85	-	33	33.15	mm
E	package width		32.85	-	33	33.15	mm
A	seated height		3.18	-	3.38	3.58	mm
e	nominal pitch		-	-	1.6	-	mm
n ₂	actual quantity of termination		-	-	350	-	



2. Package outline

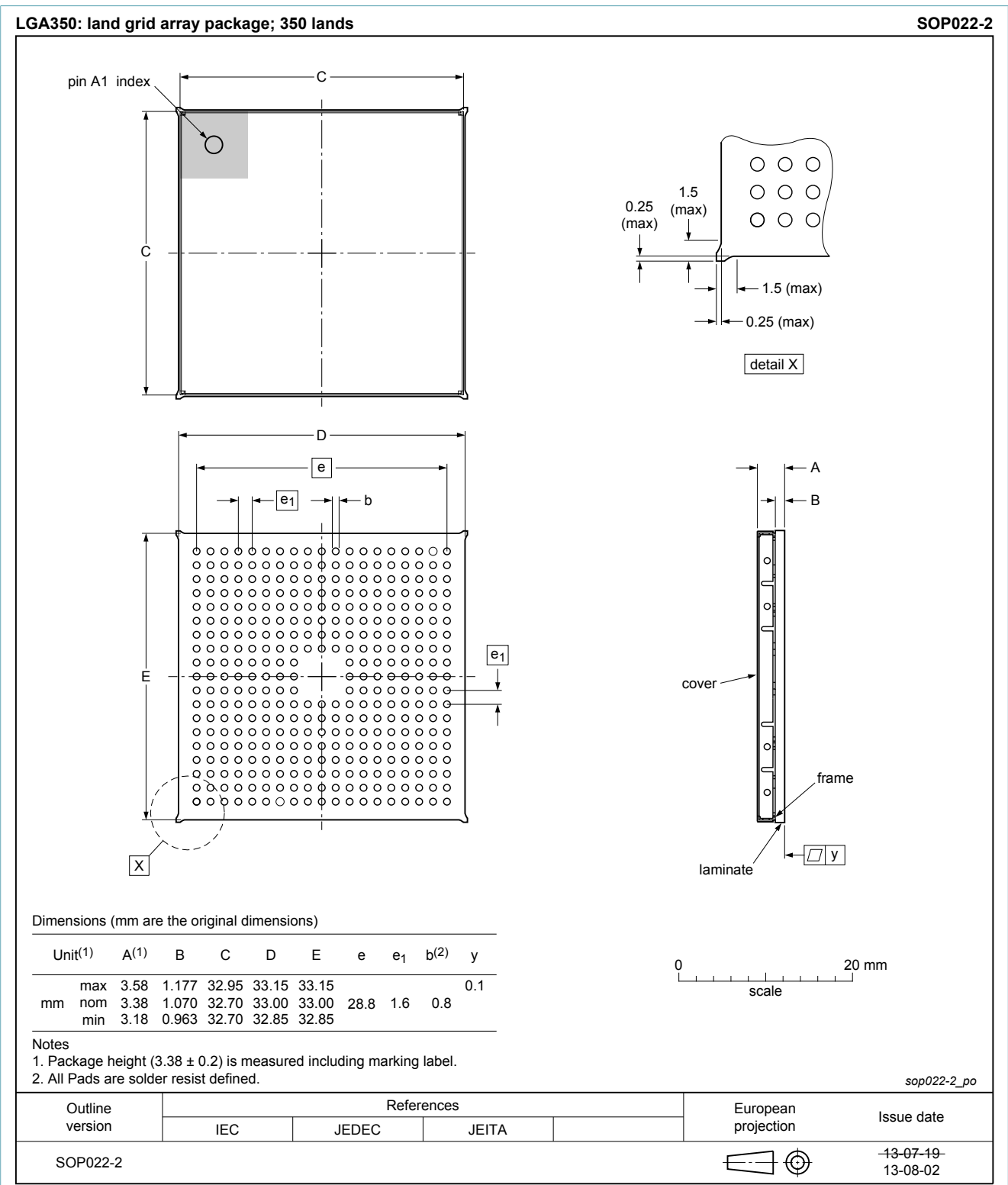


Fig. 1. Package outline LGA350 (SOP022-2)

3. Soldering

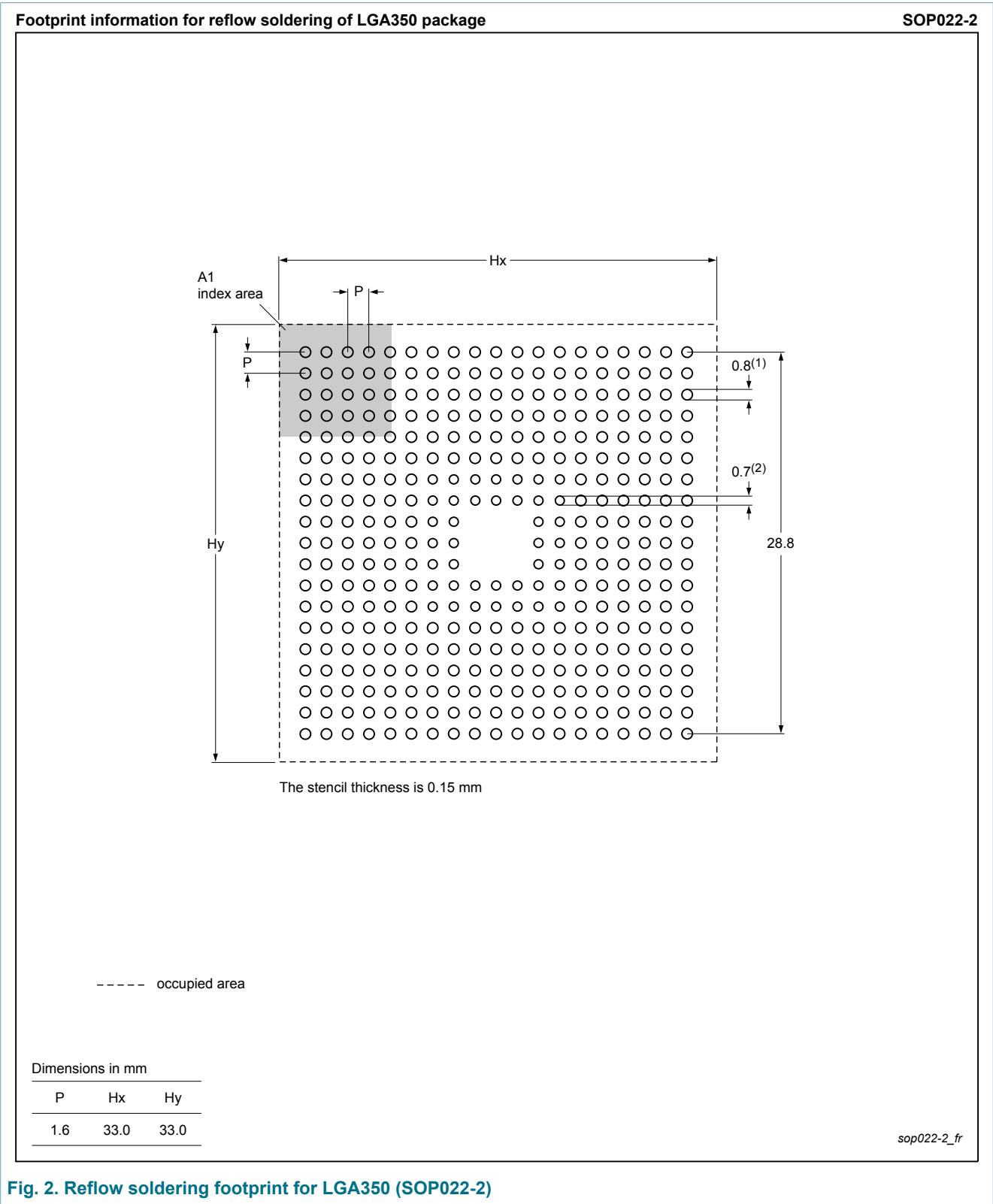


Fig. 2. Reflow soldering footprint for LGA350 (SOP022-2)

4. Legal information

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